

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"PG-PUBS INTERFERENCE SEARCH"	US-PGPUB; USPAT	OR	ON	2008/11/03 10:36
L2	343	(method process procedure) and display adj device and (conductive metal\$4) near (film layer) and substrate and eject\$4 near2 (liquid droplet) and (metal\$4 conducti\$4) near particle and ejecti\$4 nozzle and (straight linear) and resist and pattern and wiring and etch\$4 and atmosphe\$4 near pressure and plasma and pair near electrode and (insulati\$4 dielectric) near (film layer) and ((contact through) adj hole via)	US-PGPUB; USPAT	OR	ON	2008/11/03 10:49
L3	1	(method process procedure) and display adj device and (conductive metal\$4) near (film layer) and substrate and eject\$4 near2 (liquid droplet) and (metal\$4 conducti\$4) near particle and ejecti\$4 adj nozzle and (straight linear) and resist and pattern and wiring and etch\$4 and atmosphe\$4 near pressure and plasma and pair near electrode and (insulati\$4 dielectric) near	US-PGPUB; USPAT	OR	ON	2008/11/03 10:50

		(film layer) and ((contact through) adj hole via)				
L4	1	(method process procedure) and display and (conductive metal\$4) with (film layer) and substrate and eject\$4 near2 (liquid droplet) and (metal\$4 conducti \$4) near particle and ejecti\$4 adj nozzle and (straight linear) and resist and pattern and wiring and etch \$4 and atmosphe\$4 near pressure and plasma and pair near electrode and (insulati \$4 dielectric) near (film layer) and ((contact through) adj hole via)	US- PGPUB; USPAT	OR	ON	2008/11/03 10:51
L5	2	(method process procedure) and display and (conductive metal\$4) with (film layer) and substrate and eject\$4 with (liquid droplet) and (metal\$4 conducti \$4) with particle and ejecti\$4 adj nozzle and (straight linear) and resist and pattern and wiring and etch \$4 and atmosphe\$4 near pressure and plasma and pair near electrode and (insulati \$4 dielectric) near (film layer) and ((contact through) adj hole via)	US- PGPUB; USPAT	OR	ON	2008/11/03 10:52

L6	52	(method process procedure) and display and (conductive metal\$4) with (film layer) and substrate and eject\$4 with (liquid droplet) and (metal\$4 conducti\$4) with particle and ejecti\$4 adj nozzle and (straight linear) and resist and pattern and wiring and etch \$4 and atmosphe\$4 and plasma and electrode and (insulati\$4 dielectric) with (film layer) and ((contact through) adj hole via)	US-PGPUB; USPAT	OR	ON	2008/11/03 10:53
L7	0	((method process procedure) and display and (conductive metal\$4) with (film layer) and substrate and eject\$4 with (liquid droplet) and (metal\$4 conducti\$4) with particle and ejecti\$4 adj nozzle and (straight linear) and resist and pattern and wiring and etch \$4 and atmosphe\$4 and plasma and electrode and (insulati\$4 dielectric) with (film layer) and ((contact through) adj hole via)).dm.	US-PGPUB; USPAT	OR	ON	2008/11/03 10:54

11/3/08 10:57:27 AM

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